JOCT817Xh-D4P/S Series

Rev.A.1.0

The products are transistor opto-couplers in a plastic DIP4 package with different lead forming options, that infrared LED chip and photo-transistor chip are assembled on lead frame, in order to change the electricity-light-electricity. The products are widely used in transmission and conversion of digital logic, power control and switch, electric insulation and impedanc wc ! ʎ D

Soldering Temperature	T_{sol}	260	

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FIG.1: Max. Allowable LED Forward Current vs. Ambient Temperature

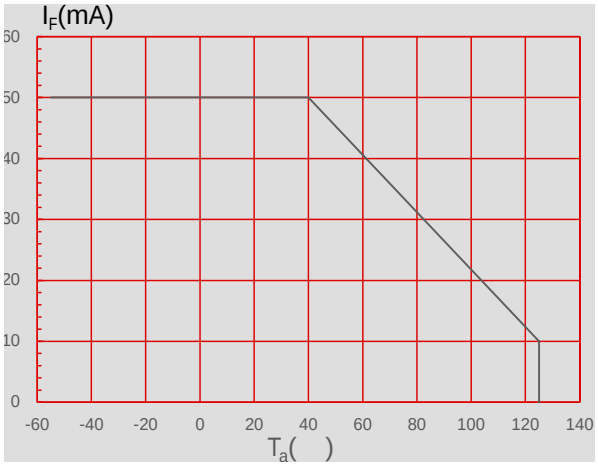


FIG.2: Collector Power Dissipation vs. Ambient Temperature

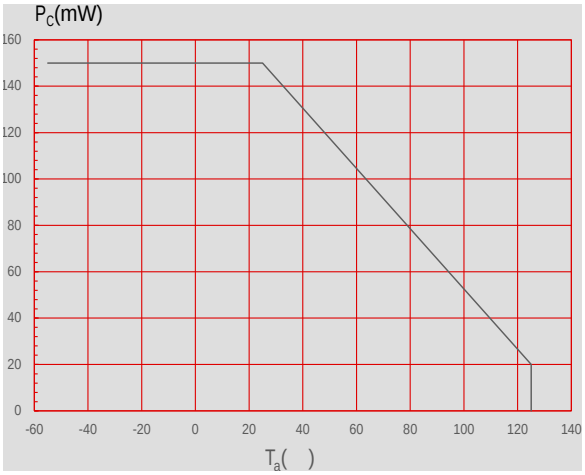


FIG.3: Forward Current vs. Forward Voltage

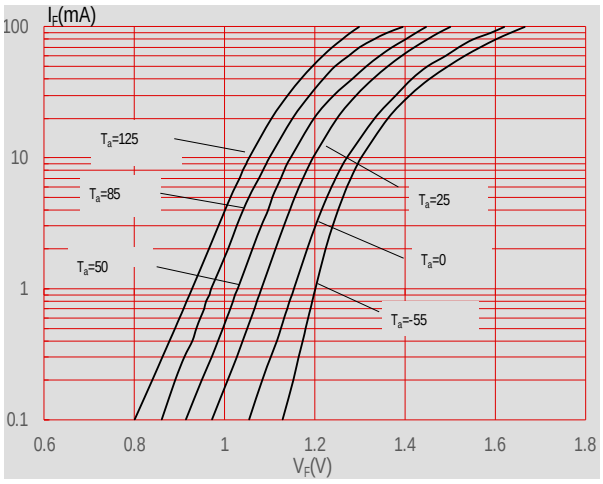


FIG.4: Normalized Collector Dark Current vs. Ambient Temperature

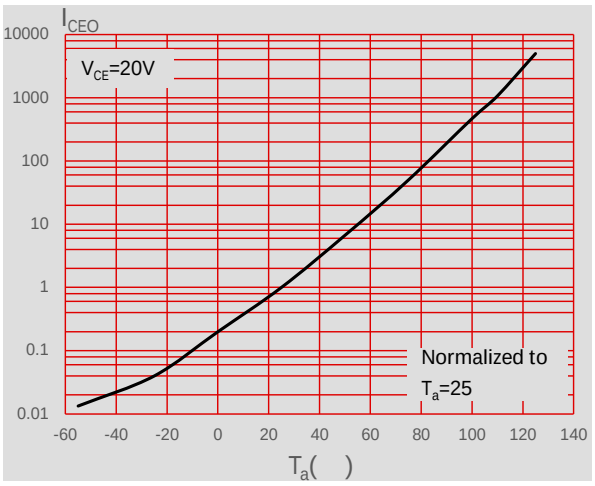


FIG.5: Collector Current vs. Collector-emitter Voltage

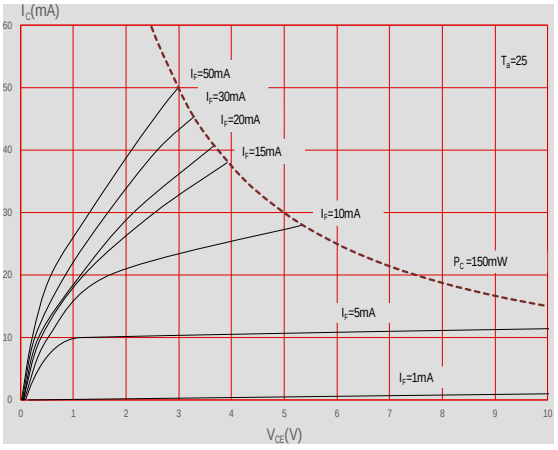


FIG.6: Normalized Current Transfer Ratio vs. Forward Current

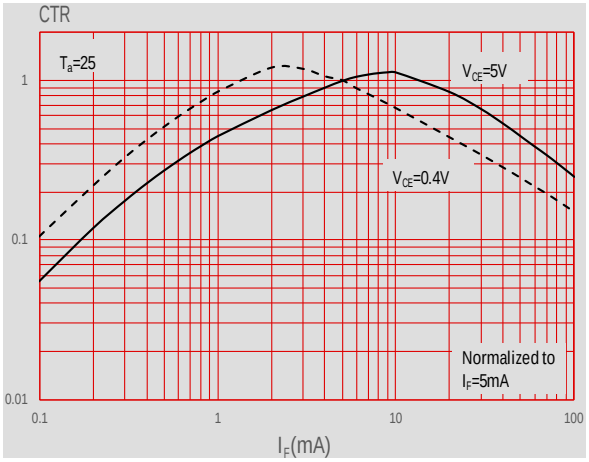


FIG.7: Normalized Current Transfer Ratio vs. Ambient Temperature

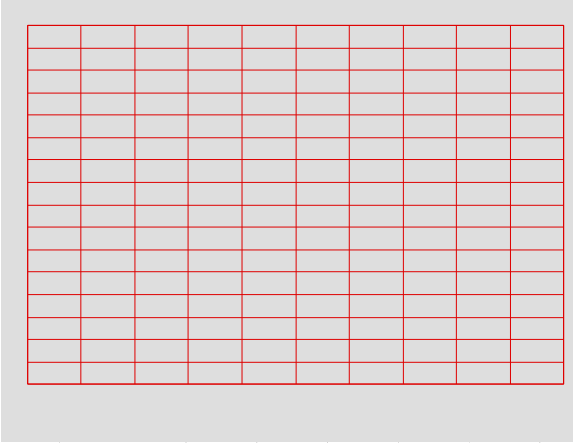
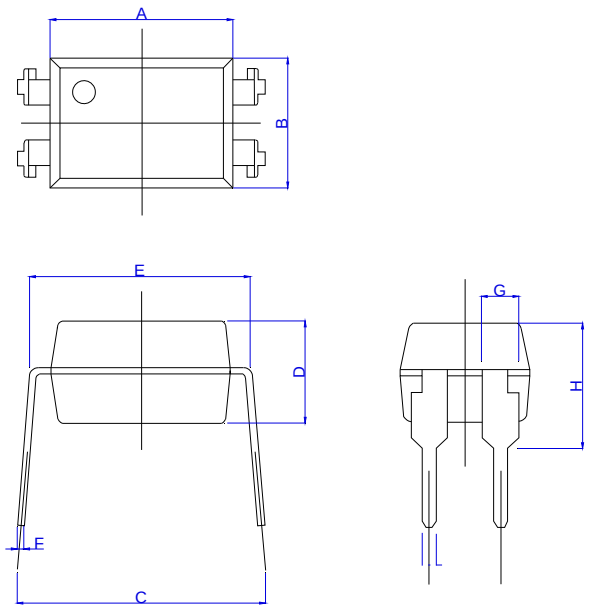


FIG.8: Normalized Collector-emitter Saturation Voltage vs. Ambient Temperature 0.

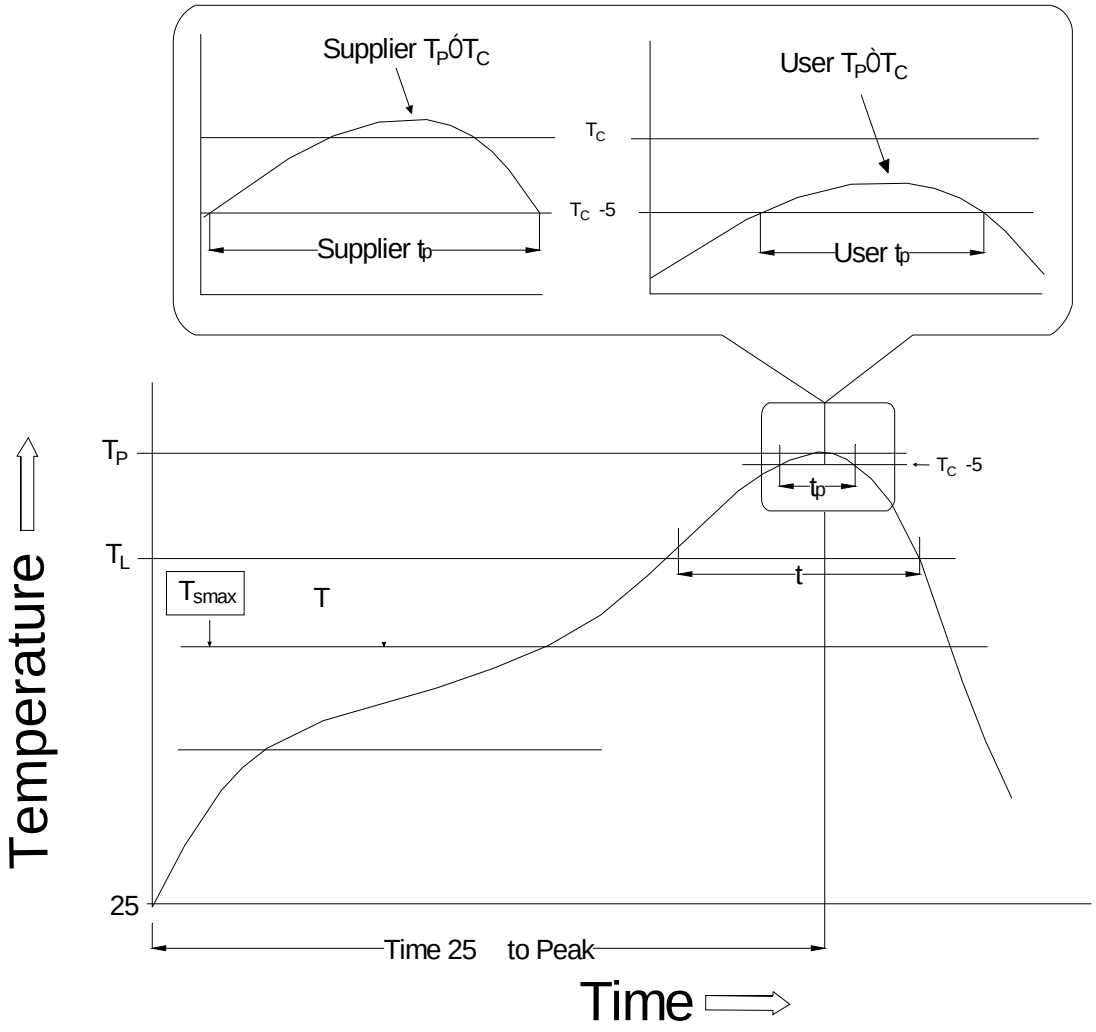
JOCT817Xh

Standard DIP Type:



JOCT817Xh **JieJie ! ȳ m D 3**




Supplier TpÓTc
User TpÒTc
Tc
Tc -5
Supplier tp
User tp
Tp
TL
Tsmax
T
tp
t
25
Time 25 to Peak
Temperature
Time



Soldering Temperature	360 ± 5
Soldering Time	3s max.